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Abstract

Electronic device as multichip module and method for producing it

The invention relates to an electronic device, a leadframe and a panel and also to a method for producing the same. The electronic device (1) has, as multichip module, two or more semiconductor chips (2, 3) which are integrated into a leadframe (7) in such a way that a placement side (8) of the leadframe (7) and the active top sides (5, 6) of the circuit chips (2, 3) are flush and have a common fine wiring plane (9). The leadframe (7) is arranged as an expanded semiconductor chip on a rewiring substrate (12).

[Figure 5]